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To the Honorable Commissi

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rd the attached original documents or copy thereof.

1. Name of conveying party(ies): a) Yoshihiro Ohtsuka b) Kazunori Nakao Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies) Name: Daicel Chemical Industries, Ltd. Internal Address: Street Address: 1, Teppocho Sakai-shi Osaka, 590 Japan City: State: ZIP: Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:  Assignment  Merger  Security Agreement  Change of Name  Other Execution Date: July 21, 1998

4. Application number(s) or patent number(s): 09/125,002 a) 6/29/98 b) 7/2/98 If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Leonard W. Sherman Internal Address: SHERMAN AND SHALLOWAY Street Address: 413 N. Washington Street City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41).....\$ 40.00  Enclosed  Authorized to be charged to deposit account 8. Deposit account number: 19-1980 (Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Leonard W. Sherman Name of Person Signing Signature Date July 31, 1998 Total number of pages including cover sheet, attachments, and document: 2

**A S S I G N M E N T**

WHEREAS, We, Yoshihiro Ohtsuka and Kazunori Nakao, residing at Room 305, 13-5, Kuba 4-chome, Otake-shi, Hiroshima, 739-06, Japan; and 31-1228, 3-3, Nankounaka, Suminoe-ku, Osaka-shi, Osaka, 559, Japan, respectively, (hereinafter referred to as Inventors), have invented certain new and useful improvements in HOT MELT ADHESIVE COMPOSITION EXCELLENT IN HEAT RESISTANCE AND COLD RESISTANCE; for which an application for United States Letters Patent was signed by us on \_\_\_\_\_; and

WHEREAS, Daicel Chemical Industries, Ltd., having a place of business at 1, Teppocho Sakai-shi, Osaka, 590 Japan (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Assignee, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Assignee as the assignee of the entire right, title and interest in and to the same, for the sole use and behoof of the said Assignee, its successors and assigns.

FURTHER, We agree that we will communicate to said Assignee or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Assignee, make all rightful oaths and generally do everything possible to aid said Assignee, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, We have hereunto set our hands this 21 day of July, 1998.

Signed in the presence of:

Witness: <u>Hiroaki Kase</u>	Signed: <u>Yoshihiro Ohtsuka</u>
Witness: <u>Shigehiro Maeda</u>	Signed: <u>Kazunori Nakao</u>